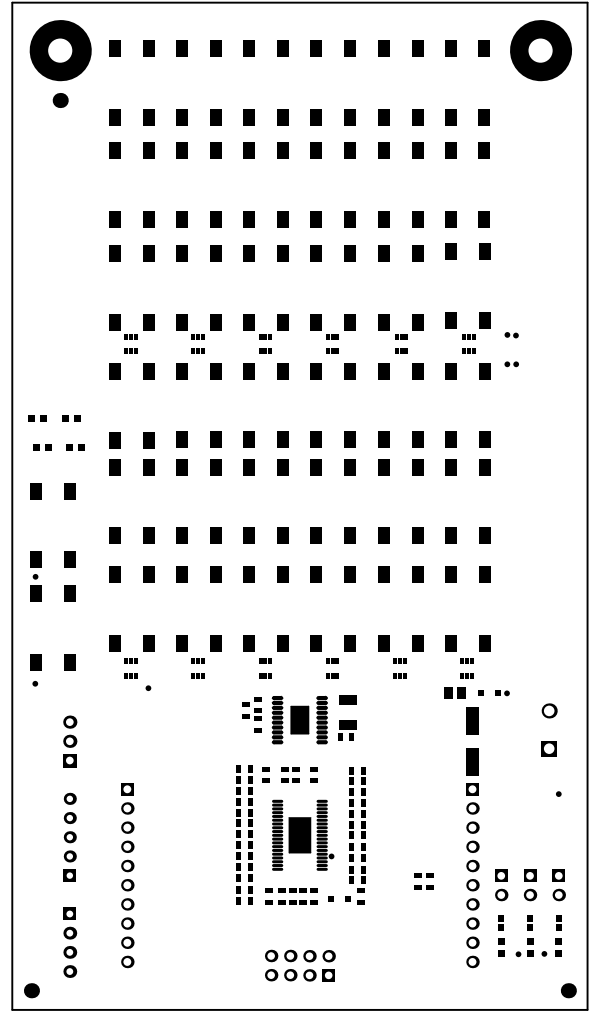
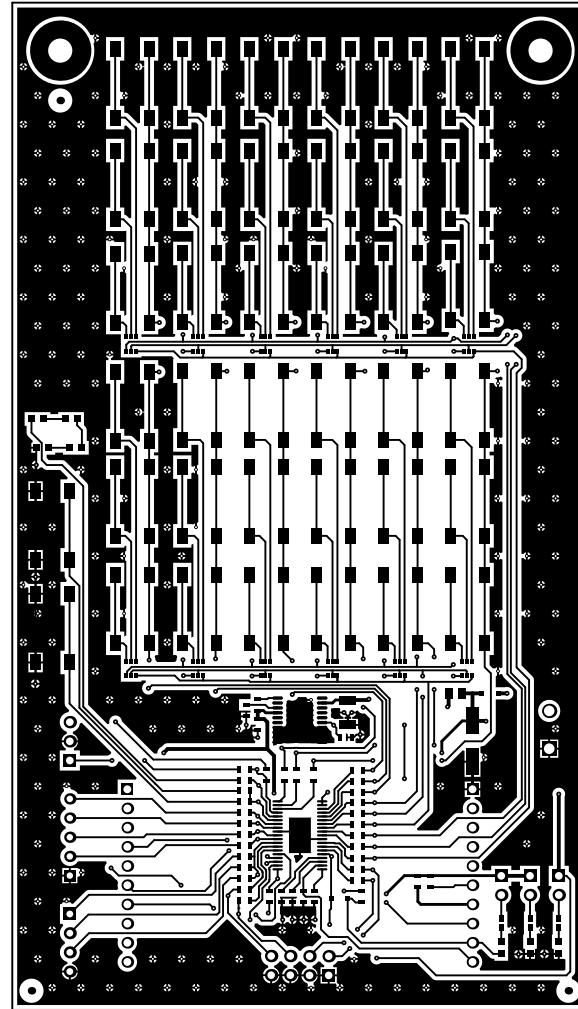


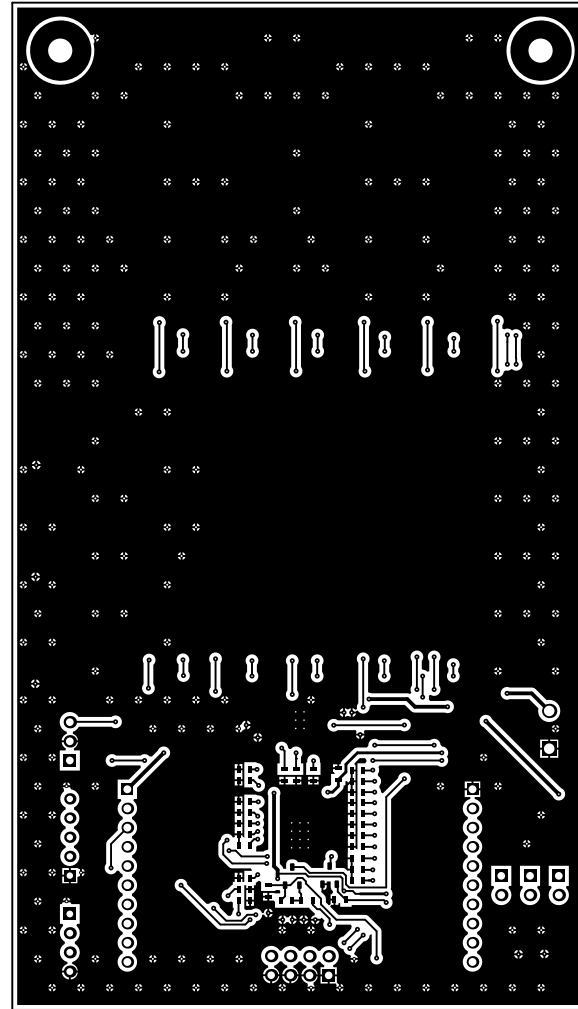
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01237		
PLOT NAME = Top Overlay	GENERATED : 12/12/2016 2:26:47 PM	TEXAS INSTRUMENTS	



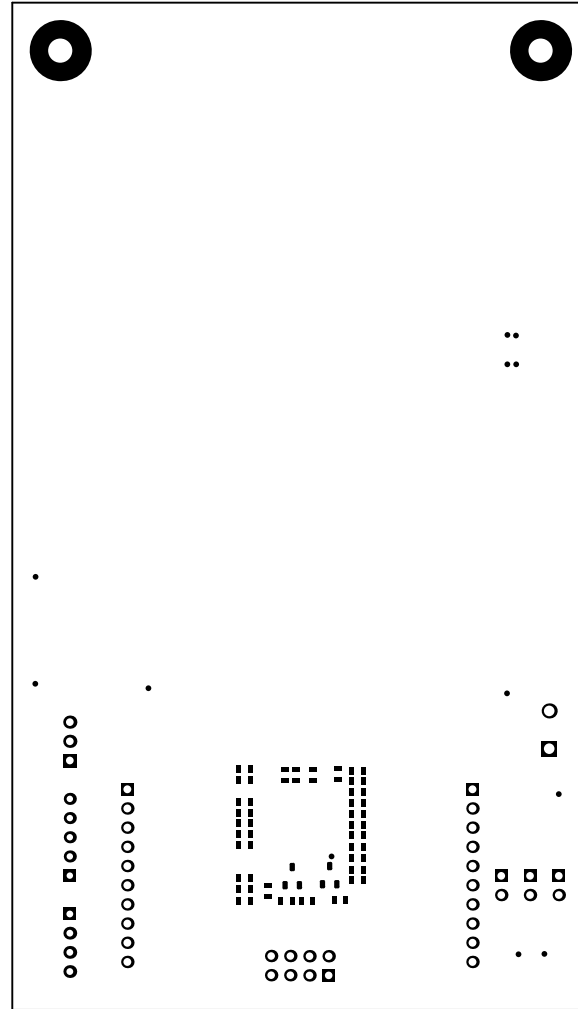
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01237		
PLOT NAME = Top Solder Mask	GENERATED : 12/12/2016 2:26:48 PM	TEXAS INSTRUMENTS	



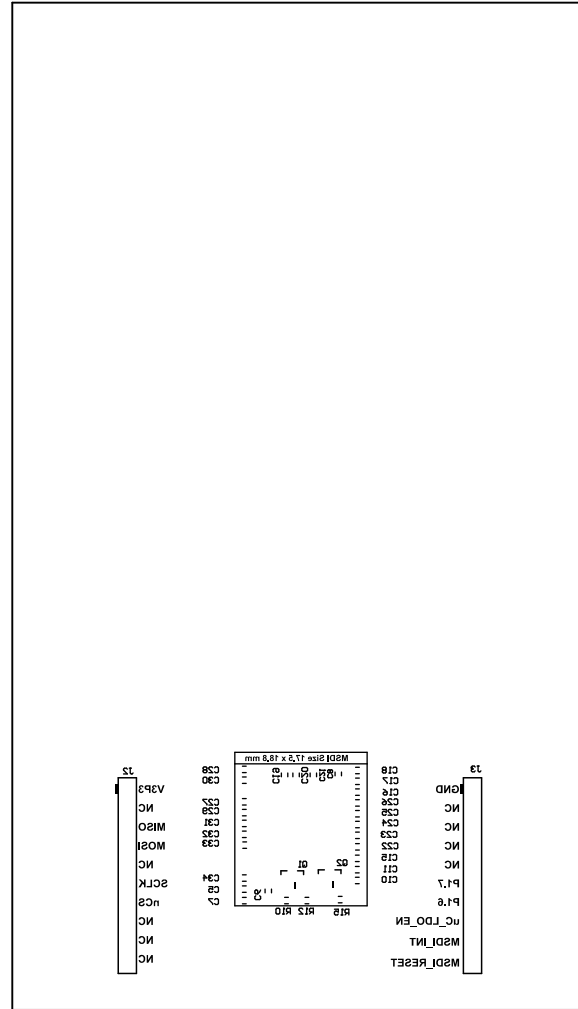
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01237		
PLOT NAME = Top Layer	GENERATED : 12/12/2016 2:26:49 PM	TEXAS INSTRUMENTS	



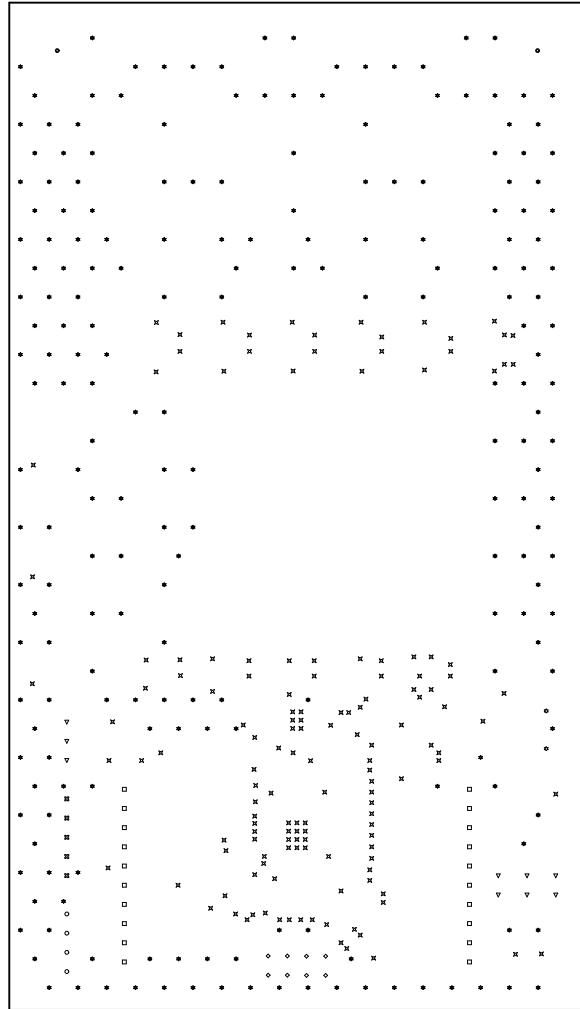
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01237		
PLOT NAME = Bottom Layer	GENERATED : 12/12/2016 2:26:50 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01237		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/12/2016 2:26:51 PM	TEXAS INSTRUMENTS	

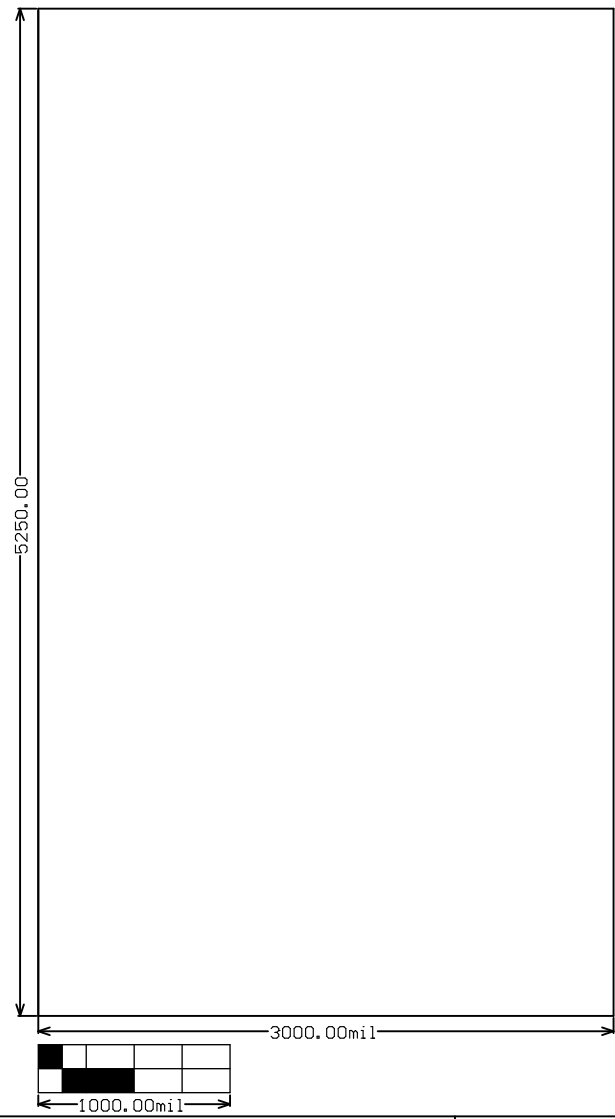


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01237		
PLOT NAME = Bottom Overlay	GENERATED : 12/12/2016 2:26:52 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	146	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
✱	214	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✖	5	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
◇	8	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
▽	9	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	20	40.94mil (1.040mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	2	55.12mil (1.400mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	2	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	410 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01237		
PLOT NAME = Drill Drawing	GENERATED : 12/12/2016 2:26:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01237	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01237		
PLOT NAME = Board Dimensions	GENERATED : 12/12/2016 2:26:55 PM	TEXAS INSTRUMENTS	

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